# DZ2J051

### Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

#### Features

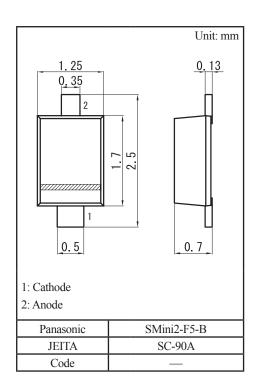
- $\bullet$  Excellent rising characteristics of zener current  $I_{\rm z}$
- $\bullet$  Low zener operating resistance  $R_{\rm Z}$
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)
- Marking Symbol: CJ, CU

#### Packaging

DZ2J051×0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

| Parameter                       | Symbol Rating    |             |    |
|---------------------------------|------------------|-------------|----|
| Repetitive peak forward current | I <sub>FRM</sub> | 200         | mA |
| Total power dissipation *1      | P <sub>T</sub>   | 200         | mW |
| Electrostatic discharge *2      | ESD              | ±15         | kV |
| Junction temperature            | Tj               | 150         | °C |
| Storage temperature             | T <sub>stg</sub> | -55 to +150 | °C |



Note) \*1: Mounted on glass epoxy print board. (45 mm  $\times$  45 mm  $\times$  1 mm)

Solder in (Recommended land pattern)

\*2: Test method:IEC61000-4-2 (C = 150 pF, R = 330  $\Omega$ , Contact discharge:10 times)

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

| Parameter                                   | Symbol          | Conditions                 | Min  | Тур | Max  | Unit  |
|---|-----------------|----------------------------|------|-----|------|-------|
| Forward voltage                             | V <sub>F</sub>  | $I_{\rm F} = 10  {\rm mA}$ |      |     | 1.0  | V     |
| Zener voltage *1, 2, 4                      | VZ              | $I_Z = 5 \text{ mA}$       | 4.85 |     | 5.36 | V     |
| Zener operating resistance                  | R <sub>Z</sub>  | $I_Z = 5 \text{ mA}$       |      |     | 60   | Ω     |
| Zener rise operating resistance             | R <sub>ZK</sub> | $I_{Z} = 1.0 \text{ mA}$   |      |     | 500  | Ω     |
| Reverse current                             | I <sub>R</sub>  | $V_{\rm R} = 2.0  {\rm V}$ |      |     | 1.0  | μΑ    |
| Temperature coefficient of zener voltage *3 | SZ              | $I_Z = 5 \text{ mA}$       |      | 0.7 |      | mV/°C |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

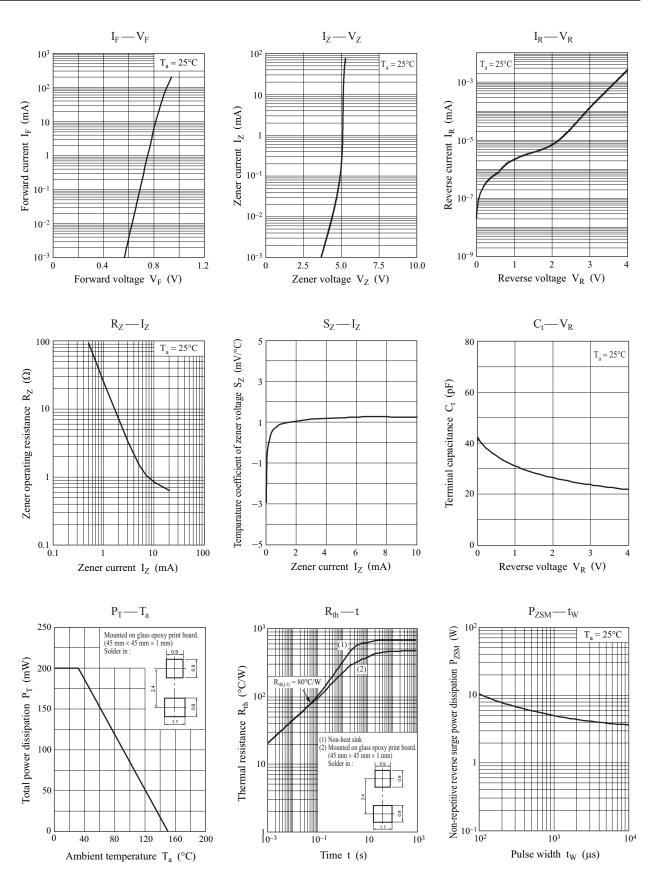
2. Absolute frequency of input and output is 5 MHz.

3. \*1: The temperature must be controlled 25°C for  $V_Z$  measurement.  $V_Z$  value measured at other temperature must be adjusted to  $V_Z$  (25°C) \*2:  $V_Z$  guaranteed 20 ms after current flow.

\*3:  $T_i = 25^{\circ}C$  to  $150^{\circ}C$ 

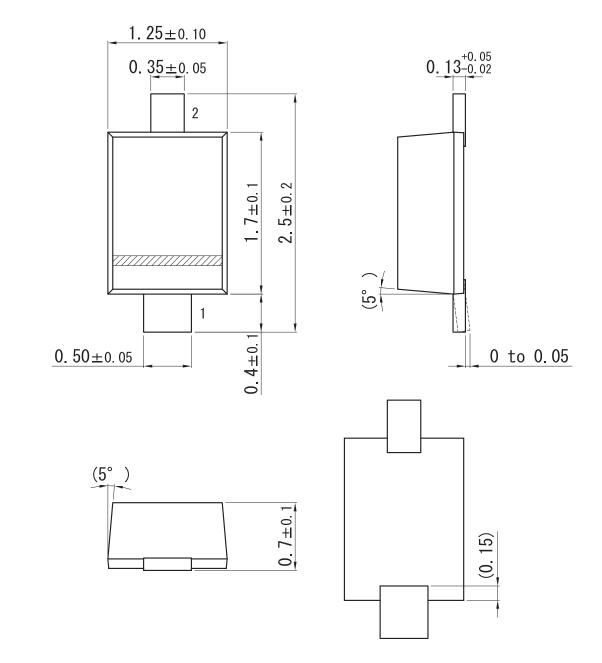
\*4: Rank classification

| Code           | М            | 0            |  |
|----------------|--------------|--------------|--|
| Rank           | М            | No-rank      |  |
| Vz             | 5.00 to 5.26 | 4.85 to 5.36 |  |
| Marking Symbol | CU           | CJ           |  |

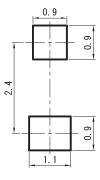


Unit: mm

SMini2-F5-B



Land Pattern (Reference) (Unit: mm)



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